

## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C4R7CA3GNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4.7pF, 25V, ±0.25pF, C0G, 0201

## A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>4R7</u> <u>C</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor						
2	Size	0201 (inch code)	L: 0.6	± 0.03 mm	W:	0.3	± 0.03	mm
3	Dielectric	C0G	<b>(8</b> )	Inner electrode		Cu		
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4	Capacitance	<b>4.7</b> pF		Termination		Cu		
⑤	Capacitance	±0.25 pF		Plating		Sn 100	)%	(Pb Free)
	tolerance		9	Product		Norma	l	
6	Rated Voltage	25 V	10	Special		Reserv	ed for t	future use
7	Thickness	$0.3 \pm 0.03$ mm	11)	Packaging		Cardbo	oard Ty	pe, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms					
Q	494 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	COG						
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)						
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder					
	is to be soldered newly	235±5℃, 5±0.5sec.					
		2) SnAg3.0Cu0.5 solder					
		245±5°C, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within ±2.5% or ±0.25pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change :	Amplitude : 1.5mm				
within ±2.5% or ±0.25pF whichever is larger		From 10Hz to 55Hz (return : 1min.)				
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)				
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs				
	within ±5% or ±0.5pF whichever is larger					
	Q: 247 min					
	IR: 1000Mohm or 50Mohm · μF					
	Whichever is Smaller					
Moisture	Capacitance change :	With rated voltage				
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs				
	Q: 115.67 min					
	IR : 500Mohm or 25Mohm · μF					
	Whichever is Smaller					
High Temperature	Capacitance change :	With 200% of the rated voltage				
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature				
	Q: 247 min	1000+48/-0hrs				
	IR : 1000Mohm or 50Mohm · μF					
	Whichever is Smaller					
Temperature	Capacitance change :	1 cycle condition				
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25°C				
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C				
		5 cycle test				

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\!\!\mathrm{C}$  , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.